PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT2676036

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
VIASYSTEMS NORTH AMERICA OPERATIONS, INC.	12/31/2013

RECEIVING PARTY DATA

Name:	VIASYSTEMS TECHNOLOGIES CORP., L.L.C.
Street Address:	101 SOUTH HANLEY ROAD
Internal Address:	SUITE 1800
City:	ST. LOUIS
State/Country:	MISSOURI
Postal Code:	63105

PROPERTY NUMBERS Total: 16

Property Type	Number
Patent Number:	8156645
Patent Number:	8510941
Patent Number:	8250751
Application Number:	13594971
Patent Number:	8453322
Patent Number:	7523545
Patent Number:	7856706
Application Number:	12938265
Patent Number:	8567053
Application Number:	14065047
Application Number:	61586691
Application Number:	13482702
Patent Number:	8020292
Application Number:	13206414

Application Number:	13400020
Application Number:	13162408

CORRESPONDENCE DATA

Fax Number: (618)655-9640
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ATTORNEY DOCKET NUMBER:	062651
NAME OF SUBMITTER:	REBECCA L. ENDSLEY, PARALEGAL
Signature:	/Rebecca L. Endsley/
Date:	01/10/2014

Total Attachments: 5
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UNITED STATES PATENT ASSIGNMENT

1. WHEREAS, **Viasystems North America Operations, Inc.** a California corporation, with offices at 101 South Hanley Road, Suite 1800, St. Louis, Missouri 63105, ("Assignor"), is the owner of the entire right, title, and interest in and to certain letters patent and patent applications throughout the world and the inventions disclosed therein; and

2. WHEREAS, **Viasystems Technologies Corp., L.L.C.**, a Delaware limited liability company, with offices at 101 South Hanley Road, Suite 1800, St. Louis, Missouri 63105 ("Assignee"), is desirous of acquiring said right, title and interest of Assignor;

3. NOW, THEREFORE, in consideration of the sum of one dollar ($1.00) and other good and valuable consideration by Assignee to Assignor in hand paid, receipt of all of which is hereby acknowledged, Assignor has agreed to and does hereby sell, assign and transfer unto Assignee, its successors and assigns, all of Assignor's right, title and interest in and throughout the world, in and to said letters patent and patent application and all reissues thereof and reexamination certificates therefore, and the inventions disclosed therein, including Assignor's full right to sue for and recover all damages recoverable from past infringements of said letters patent; including specifically, without limiting the generality of the foregoing, the worldwide letters patent and patent applications listed in Appendix A; and Assignor has further agreed to and does hereby sell, assign and transfer unto Assignee, its successors and assigns, all of Assignor's right, title and interest in and throughout the world in and to said inventions, any other patent applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on said worldwide letters patent or patent applications or in whole or in part on said inventions, and any and all letters patent (including continuations and extensions thereof) of any country which have been or may be granted on any of the aforesaid patent applications or on said inventions or any part thereof; including, specifically, without limiting the generality of the foregoing, the worldwide letters patent and patent applications listed in Appendix A.

4. TO BE HELD AND ENJOYED BY Assignee, its successors and assigns, to the full ends of the respective terms for which said patents have been or may be granted, as fully and entirely as the same would have been held and enjoyed by Assignor had this sale and assignment not been made.

5. AND Assignor hereby authorizes and requests the Patent Offices of the countries wherein said patent applications are filed to issue any and all letters patent which may be granted upon said foreign country patent applications to Assignee, its successors and assigns.

6. AND Assignor hereby agrees to execute without further consideration any further lawful documents and any further assurances, and any provisional, non-provisional, divisional, continuing, reissue or other applications for patents of any country, that may be deemed necessary by said Assignee, its successors or assigns fully to secure its interest as aforesaid in and to said inventions or any part thereof, and in and to said several patents or any of them.

7. AND Assignor covenants that Assignor has granted no right or license to make, use or sell said inventions to anyone except said Assignee, that prior to the execution of this deed, Assignor's right, title, and interest in said inventions has not been otherwise encumbered, and that Assignor has not executed and will not execute any instrument in conflict herewith.

ASSIGNOR
Viasystems North America Operations, Inc.

By: Daniel J. Weber
Vice President & General Counsel

Date: 12/31/13

ACKNOWLEDGMENT

STATE OF Missouri)
) SS.
CITY OF Saint Louis)

On this 31 day of December, 2013, before me personally appeared Daniel J. Weber, to me known to be the person described in, and who executed the foregoing instrument, and duly acknowledged to me that she executed the same for the uses and purposes therein set forth.

Notary Public

My Commission expires: 12-26-2014

[SEAL]

RONALD C. HOVIS
Notary Public - Notary Seal
STATE OF MISSOURI
St. Louis County
My Commission Expires: Dec. 26, 2014
Commission # 10415605

ASSIGNEE
Viasystems Technologies Corp., L.L.C..

By: Daniel J. Weber
Vice President & General Counsel
Date: 12/31/13

ACKNOWLEDGMENT

STATE OF Missouri)
) SS.
CITY OF Saint Louis)

On this 31 day of December, 2013, before me personally appeared, Daniel J. Weber, to me known to be the person described in, and who executed the foregoing instrument, and duly acknowledged to me that she executed the same for the uses and purposes therein set forth.

Notary Public

My Commission expires: 12-26 2014

[SEAL]

RONALD C. HOVIS
Notary Public - Notary Seal
STATE OF MISSOURI
St. Louis County
My Commission Expires: Dec. 26, 2014
Commission # 10415605

Appendix A

Polsinelli No.	Country	Title	Application No.	Patent No.
062651-444267	US	METHOD OF MANUFACTUrRING A MULTILAYER PRINTED WIRING BOARD WITH COPPER WRAP PLATED HOLE	12/157,021	8,156,645
062651-444269	US	METHODS OF MANUFACTURING A PRINTED WIRING BOARD HAVING COPPER WRAP PLATED HOLE	13/399,995	8,510,941
062651-444271	US	METHOD OF MANUFACTURING A PRINTED CIRCUIT BOARD	12/070,811	8,250,751
062651-445960	US	METHOD OF MANUFACTURING A PRINTED CIRCUIT BOARD	13/594,971	
062651-444330	US	MANUFACTURING METHODS OF MULTILAYER PRINTED CIRCUIT BOARD HAVING STACKED VIA	12/539,172	8,453,322
062651-444247	US	METHODS OF MANUFACTURING PRINTED CIRCUIT BOARDS WITH STACKED MICRO VIAS	11/706,473	7,523,545
062651-444261	US	METHODS OF MANUFACTURING PRINTED CIRCUIT BOARDS WITH STACKED MICRO VIAS	12/381,925	7,856,706
062651-444262	US	METHODS OF MANUFACTURING PRINTED CIRCUIT BOARDS WITH STACKED MICRO VIAS	12/938,265	
062651-444345	US	METHODS OF MANUFACTURING PRINTED CIRCUIT BOARDS	13/153,254	8,567,053
062651-464804	US	SYSTEMS AND METHODS OF MANUFACTURING PRINTED CIRCUIT BOARDS USING BLIND AND INTERNAL MICRO VIAS TO COUPLE SUBASSEMBLIES	14/065,047	
062651-444369	US	PRINTED CIRCUIT BOARD WITH EMBEDDED HEATER	61/586,691	

Appendix A

062651-445958	US	PRINTED CIRCUIT BOARD WITH EMBEDDED HEATER	13/482,702	
062651-444328	US	METHODS OF MANUFACTURING PRINTED CIRCUIT BOARDS	12/772,086	8,020,292
062651-444304	US	METHODS OF MANUFACTURING PRINTED CIRCUIT BOARDS USING PARALLEL PROCESSES TO INTERCONNECT WITH SUBASSEMBLIES	13/206,414	
062651-444367	US	METHOD FOR ANCHORING A CONDUCTIVE CAP ON A FILLED VIA IN A PRINTED CIRCUIT BOARD AND PRINTED CIRCUIT BOARD WITH AN ANCHORED CONDUCTIVE CAP	13/400,020	
062651-444366	US	SYSTEMS AND METHODS FOR REDUCING OVERHANG ON ELECTROPLATED SURFACES OF PRINTED CIRCUIT BOARD	13/162,408	